



## SPEAKER BIOS



### **John Miller**

Vice President – Global Policy and Law, Cybersecurity and Privacy

#### Information Technology Industry Council (ITI)

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ITI is a 100-year-old global trade association representing the world's leading technology and innovation companies from all corners of the information and communications technology (ICT) sector, including hardware, software, digital services, cybersecurity, semiconductor, network equipment, Internet companies, and companies using technology to fundamentally evolve their businesses. Miller currently drives ITI's global policy strategy development and worldwide government influencing activities on cybersecurity, privacy and data protection, surveillance, encryption and government access, and related global policy issues.

Prior to his tenure at ITI, Miller worked for nearly a decade in the Global Public Policy organization at Intel Corporation. In his most recent position at Intel, Miller served as the company's Director of Cybersecurity Policy and Government Relations and Managing Counsel, leading Intel's U.S. cybersecurity policy strategy and advocacy efforts across all federal government stakeholders, including Intel's engagement on and implementation of the Cybersecurity Framework pursuant to Executive Order 13636: Improving Critical Infrastructure Cybersecurity. At Intel Miller also spearheaded the company's global policy strategy development and advocacy efforts on issues including cybersecurity threat information sharing, electronic surveillance and communications privacy, and the intersection of human rights, civil liberties and technology.



Earlier in his career, Miller led Intel's privacy and security policy strategy and outreach efforts in the Asia-Pacific region. A proven IT industry leader on security and privacy, Miller previously chaired and currently serves as an elected officer (Treasurer) of the Information Technology Sector Coordinating Council, the primary IT sector entity responsible for coordinating with the Department of Homeland Security on a wide range of critical infrastructure protection and cybersecurity policy issues. Miller also currently serves as a member of the Future of Privacy Forum Advisory Board.

Earlier in his career, Miller was an attorney in private practice representing technology, telecommunications, media and other corporate clients and executives in a variety of complex business and intellectual property litigations, regulatory matters, and white collar criminal investigations.

John received his J.D. from the University of Wisconsin Law School, where he served as Articles Editor of the Wisconsin Law Review. John graduated from Hamilton College with a B.A. in Government, summa cum laude, and was a graduate fellow in social and political thought at Vanderbilt University



**PHILIP M. PIQUEIRA**  
Vice President – Global Standard

Underwriters Laboratories

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Prior to accepting his position with UL, he was the Global Standards Leader for the General Electric Industrial Solutions Business, and had been with General Electric for 35 years. During that time he had held a number of engineering positions including the managerial responsibility for all overcurrent electrical protective devices. He also had the responsibility for unifying and integrating the Industrial Solutions standards activities on a global basis and was active on several standards organizations including the United States National Committee of the IEC, the American National Standards Institute, and the National Electrical Manufacturers Association. Mr. Piqueira is the Immediate Past President of the United States National Committee of the IEC and is a member of the ANSI Board of Directors. He was also the recipient of NEMA's prestigious "Kite and Key" award in 2002 for standards leadership, ANSI's Meritorious Service Award in 2007 for contributions to the U.S. voluntary standardization system, and the Astin-Polk International Standards Medal in 2015 for promoting trade.

Mr. Piqueira has a Bachelor of Science Degree in Mechanical Engineering from Worcester Polytechnic Institute and a Master of Science Degree in Mechanical Engineering from Rensselaer Polytechnic Institute. He is also a Registered Professional Engineer from the State of Connecticut.



**Edward G. Tiedemann, Jr.**

Senior Vice President, Engineering; QUALCOMM Fellow

QUALCOMM Technologies, Inc.

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Dr. Edward G. Tiedemann, Jr. is a QUALCOMM Fellow and a Senior Vice President of Engineering at QUALCOMM. He leads QUALCOMM's worldwide standardization and industry organization activities. Dr. Tiedemann was instrumental in the design and development of the TIA/EIA/IS-95 CDMA system, also called cdmaOne™. He led QUALCOMM's and much of the industry's efforts in the design and development of the third-generation cdma2000® system. For many years, he chaired the 3GPP2 physical layer working group. He led the offline industry group on M2M convergence, which resulted in oneM2M. Dr. Tiedemann holds over 200 US patents and has participated in many papers, conference lectures, and industry panels. Dr. Tiedemann was General Chair of GLOBECOM 2015, one of the IEEE Communications Society's two flagship conferences.

Prior to becoming involved with terrestrial wireless communications, Dr. Tiedemann was involved with numerous commercial and military satellite systems. From 1977 to 1988, Dr. Tiedemann was at MIT Lincoln Laboratory, where he worked on mmWave satellite communications systems. Dr. Tiedemann holds the Ph.D. degree from MIT where he worked in the areas of queueing theory and communications networks. He holds the Master of Science degree from Purdue University where he worked on bandwidth efficient modulation. He also holds the Bachelor of Science degree from Virginia Polytechnic Institute and State University (Va Tech).

Dr. Tiedemann is past chairman of the Advisory Board of the College of Engineering at Virginia Polytechnic Institute and State University (Va Tech). Dr. Tiedemann currently sits on the Advisory Board of the Purdue University School of Electrical and Computer



Engineering. He is on the Board of Directors of the Open Mobile Alliance, Open Connectivity Foundation, and the MulteFire Alliance. He is on the Board of Overseers of the Peabody-Essex Museum.

In 2008, Dr. Tiedemann received the 3G-CDMA Industry Achievement Award for Industry Leadership from the CDMA Development Group (CDG) for his “long-running contribution to CDMA development and standardization.” He received the Global IT Innovator & Leadership Award from Yonsei University in Korea in 2009, the 2010 Virginia Tech College of Engineering Distinguished Alumni Service Award, and in 2014 became a member of the Virginia Tech Academy of Engineering Excellence. He has received both the Purdue University College of Engineering Distinguished Engineering Alumnus and the Purdue University Outstanding Electrical and Computer Engineer Awards.